(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
27 February 2003 (27.02.2003)

PCT

(10) International Publication Number
WO 03/017347 A1

(51) International Patent Classification[7]: H01L 21/304

(21) International Application Number: PCT/KR01/01464

(22) International Filing Date: 29 August 2001 (29.08.2001)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
2001/49354 16 August 2001 (16.08.2001) KR

(71) Applicant *(for all designated States except US)*: **SKC CO., LTD.** [KR/KR]; 633, Jeongja-dong, Jangan-gu, Suwon-si, Kyunggi-do, 440-300 (KR).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **PARK, In-Ha** [KR/KR]; 210-2302 Sunkyoung-2nd Apt., 368-1 Uoo-jeong-dong, Joong-ku, Ulsan 681-816 (KR). **KIM, Jae-Seok** [KR/KR]; 210-2302 Sunkyoung-2nd Apt., 368-1 Uoojeong-dong, Joong-ku, Ulsan 681-816 (KR). **HWANG, In-Ju** [KR/KR]; 210-2304 Sunkyoung-2nd Apt., 368-1 Uoojeong-dong, Joong-ku, Ulsan 681-816 (KR). **KWON, Tae-Kyoung** [KR/KR]; 210-2203 Sunky-oung-2nd Apt., 368-1 Uoojeong-dong, Joong-ku, Ulsan 681-816 (KR).

(74) Agents: **LEE, Chul** et al.; 2F. Changsang-Building, 1543-12 Seocho-3dong, Seocho-ku, Seoul 137-872 (KR).

(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW.

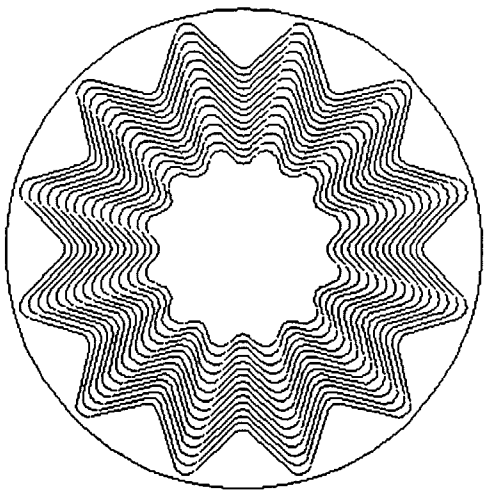
(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

WO 03/017347 A1

(54) Title: CHEMICAL MECHANICAL POLISHING PAD HAVING WAVE-SHAPED GROOVES



(57) Abstract: Disclosed is a chemical mechanical polishing pad formed at a polishing surface thereof with a plurality of concentric wave-shaped grooves having different radiuses while having the same shape. Each groove has a desired depth, width, and shape. The chemical mechanical polishing pad provides effects of effectively controlling a flow of slurry during a polishing process, thereby achieving a stability in the polishing process in terms of a polishing rate, and achieving an enhancement in the planarization of a wafer.